

LARGE CURRENT MULTILAYER CHIP BEADS / LCB TYPE

FEATURES

- ◆ Low DCR, small package
- ◆ High current handling capacity
- ◆ Nickel barrier terminations provide excellent solder heat resistance
- ◆ Suitable for flow and reflow soldering and high current applications

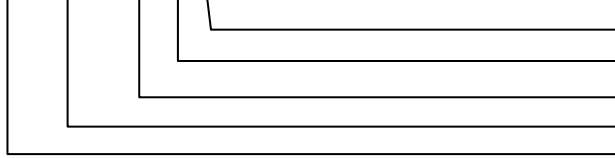


APPLICATIONS

- ◆ Electronic games
- ◆ Personal computers Hard disk drivers and other electronic equipments

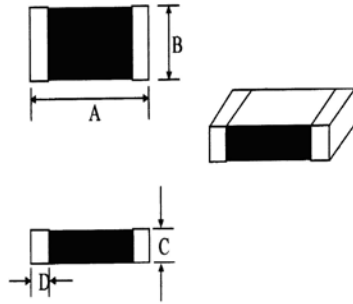
ORDERING CODE

LCB 2012 - 121 □-N



Note: lead-free
Tolerance (Y:±25%)
Inductance
Dimension (AxB)
Product Symbol

DIMENSIONS (UNIT: mm)

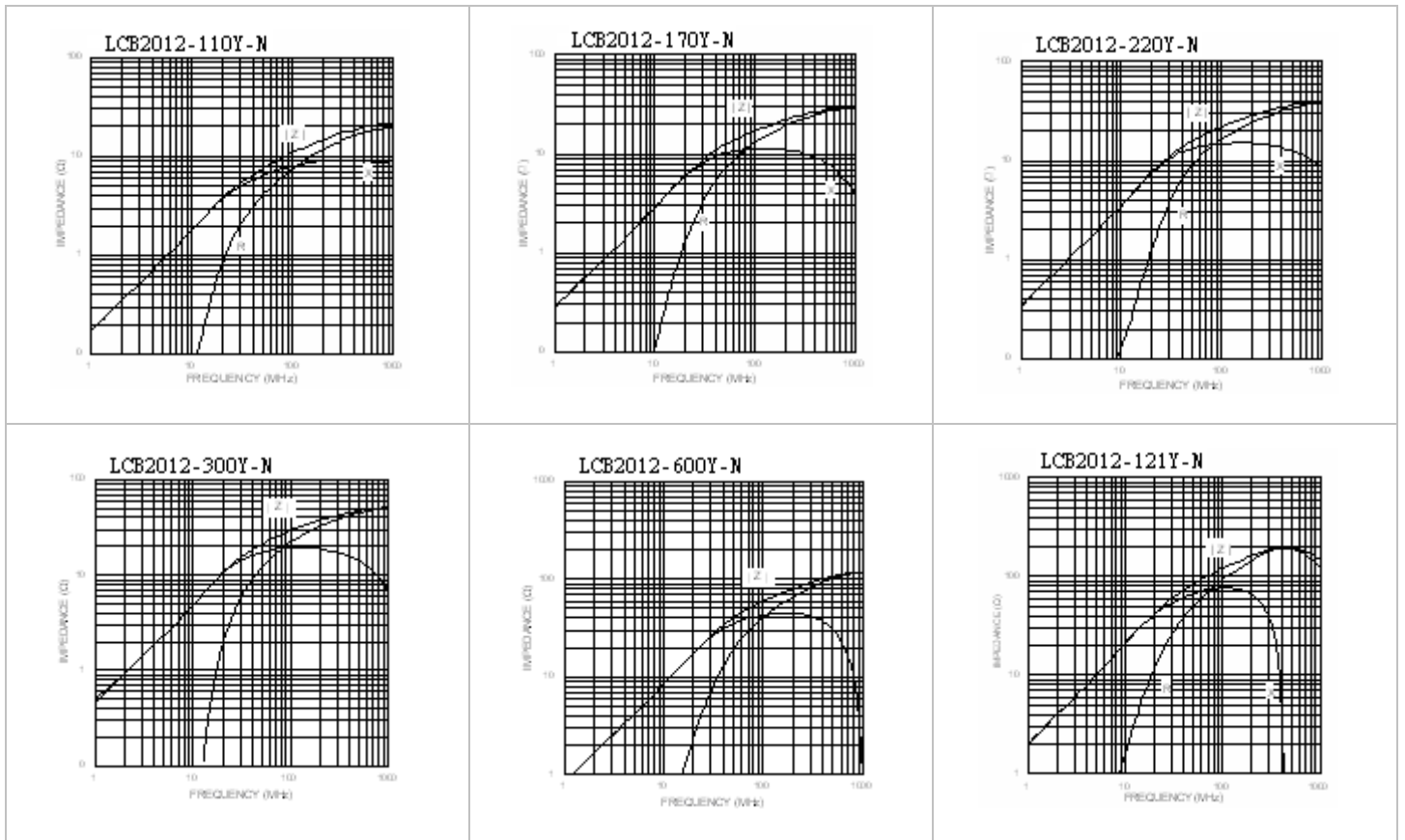


A	2.0 ± 0.2	m/m
B	1.2 ± 0.2	m/m
C	0.9 ± 0.2	m/m
D	0.5 ± 0.3	m/m

LARGE CURRENT MULTILAYER CHIP BEADS / LCB TYPE

ELECTRICAL CHARACTERISTICS LCB2012

Part No.	Impedance(Ω) AT 100MHz	DC Resistance(Ω) Max	Rated Current(A) Max
LCB 2012-110 □-N	11	0.010	6.0
LCB 2012-170 □-N	17	0.010	6.0
LCB 2012-220 □-N	22	0.010	6.0
LCB 2012-300 □-N	30	0.030	4.0
LCB 2012-600 □-N	60	0.050	3.0
LCB 2012-121 □-N	120	0.080	2.5
LCB 2012-221 □-N	220	0.100	2.0
LCB 2012-301 □-N	300	0.100	2.0
LCB 2012-601 □-N	600	0.300	1.0
LCB 2012-102 □-N	1000	0.300	1.0

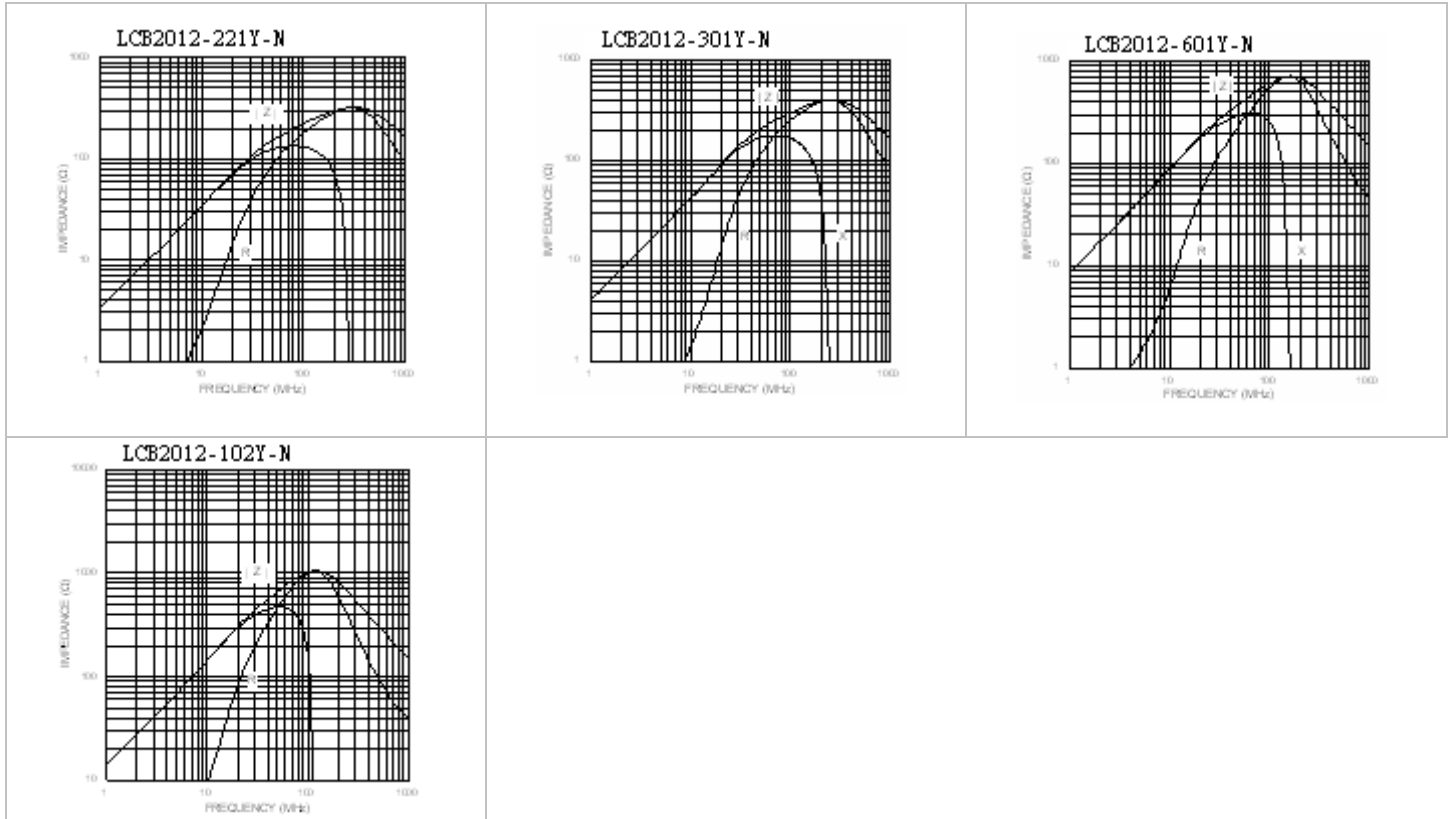


CORE MASTER ENTERPRISE CO., LTD.

<http://www.coremaster.com.tw>



LARGE CURRENT MULTILAYER CHIP BEADS / LCB TYPE



CORE MASTER ENTERPRISE CO., LTD.

<http://www.coremaster.com.tw>

